

Chip Scale Review

2015 Editorial Calendar

January • February

Semiconductor industry market update	<ul style="list-style-type: none"> • SEMI European 3D TSV Summit Grenoble, France (Jan 19-21) • APEX Expo San Diego, CA (February 24-26) • BiTS Workshop Mesa, AZ (March 15-18) • IMAPS Device Packaging (DPC) Fountain Hills, AZ (March 16-19) • SEMICON China Shanghai China (March 17-19) • Productronica China Shanghai China (March 17-19)
Next generation device packaging	
3D TSVs	
Bonding challenges for 3D ICs	
3D topography inspection for HVM	
Solid state laser ablation	
Wafer probing	
Advances in test and burn-in sockets	

International Directory of Test and Burn-in Socket Suppliers

Ad Space Close Jan 16 - Ad Materials Deadline Jan 23

March • April

Future of mobile packaging & integration challenges	<ul style="list-style-type: none"> • SEMICON South East Asia Penang, Malaysia (Apr 22-24)
RF probe technologies	
Electronic packaging materials	
FOWLP technology	
Flip-chip packaging	
3D MEMS WLP	
Inspection and metrology for advanced wafer packaging	
OSATS update	

International Directory of IC Packaging Foundries

Ad Space Close Feb 13 - Materials Close Feb 19

May • June

Interconnect technology	<ul style="list-style-type: none"> • MEPTEC MEMS Technology San Jose, CA (May 20) • IoT Symposium San Jose, CA (May 21) • ECTC San Diego, CA (May 26-29) • IMAPS Advanced Technology Workshop Dearborn, MI (June 3-4) • IEEE/SW Test Workshop (SWTW) San Diego, CA (June 7-10) • SEMI – Packaging Technical Seminar Porto, Portugal (June 18) • SEMICON West San Francisco, CA (July 14-16)
Thermal management of ICs	
Interposer reliability	
Wafer-level CSPs	
Thin wafer-handling	
MEMS Standards and Roadmap	
Dispensing technologies	
Reducing the cost-of-test	
Burn-in & test of packaged ICs*	
Inline monitoring of advanced packaging processes	

*Awarded to best paper from BiTS Workshop 2015

Ad Space Close April 4 - Ad Materials Close April 10

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July • August

Plasma cleaning technologies	<ul style="list-style-type: none"> • SEMICON Taiwan Taipei, Taiwan (Sept 2-4) • MEPTEC Medical Microelectronics Conference Portland, OR (Sept 16-17) • SEMI European MEMS Summit Milan, Italy (Sept 17-18)
Failure analysis	
Collaboration in materials and processing technology	
Metrology & defect inspection	
Discrete power devices	
Cu pillar bumping	
MEMS IoT	
Solder reliability	

Ad Space Close Jun 6 - Ad Materials Close Jun 12

September • October

System scaling for smart mobile systems	<ul style="list-style-type: none"> • SEMICON Europa Dresden, Germany (Oct 6-8) • International Test Conference (ITC) Anaheim, CA (Oct 6 - 8) • IWLPC-International Wafer-Level Packaging Conference & Exhibition San Jose, CA (Oct 13 -15) • IMAPS 2015 Orlando, FL (Oct 26-29) • Productronica Munich, Germany (Nov 10-13) • MEMS Executive Congress Napa, CA (TBD)
Interposers	
Next generation SiP	
Wafer-level packaging processes and performance	
Test trends	
Fan out wafer level packaging	
Wirebonding	
Design-for-test for stacked ICs	
Packaging, assembly and test in Europe	

Ad Space Close Aug 15 - Ad Materials Close Aug 21

November • December

Recent advances in 3D package reliability	<ul style="list-style-type: none"> • RTI 3D ASIP Conference Burlingame, CA (Dec 9-11) • SEMICON Japan Tokyo, Japan (Dec 16-18) • SEMI European 3D TSV Summit 2016 Grenoble, France (TBD)
Die stacking	
Heterogeneous integration	
Future of packaging	
3D IC standards update	
Underfill, encapsulants, and adhesives	
PoP	
MEMS automotive applications	

Ad Space Close Oct 10 - Materials Close Oct 16

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